

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): William W. Feng, et al.
Title: Method and system for numerically simulating foam-like material in finite element analysis
Serial No.: 10/783,562
Confirmation No.: 7548
Filing Date: 03/19/2004
Examiner: Juan Carlos Ochoa
Group Art Unit: 2123
Docket No: LSTC-004
Customer No: 37804

Oct. 30, 2007

Mail Stop: Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Response to Notice of Allowance

Dear Sir:

In response to the Notice of Allowance and Issue Fee Due mailed October 29, 2007, Applicant submits the following items:

1. An original copy of Issue Fee Transmittal;
2. A payment of \$720 as the issue fee.

REMARKS

Applicant appreciates the Examiner for allowing this application. It is hereby respectfully submitted that the enclosed items complete the requirement for the issuance of the above-identified application and FIG. 6 be used for the cover sheet of the patent to be issued. Please contact the undersigned at (408)255-6853, if there are any questions.

I hereby certify that this correspondence is being transmitted to the Commissioner for Patents via the Office electronic filing system on the date stated below.

Date: Oct. 30, 2007

Signature: /Roger H. Chu, Reg.# 52745/

Roger H. Chu

Respectfully submitted,

/Roger H. Chu, Reg.# 52745/

Roger H. Chu
Registration No. 52,745